Product Change Notification - JAON-04CYDE005  (Printer Friendly)

Date: 13 May 2015

Notification subject: CCB 1620 Initial Notice: Qualification of MMT assembly site for selected products in 40L PDIP package using palladium coated copper (PdCu) bond wire,

Notification text:

PCN Status:
Initial notification

Microchip Parts Affected:
See attachments of affected catalog part numbers (CPN) labeled as... PCN_JAON-04CYDE005_Affected_CPN.xls
PCN_JAON-04CYDE005_Affected_CPN.pdf

Description of Change:
Qualification of MMT assembly site for selected products in 40L PDIP package using palladium coated copper (PdCu) bond wire.

Pre Change:
MTA1 assembly site.

Post Change:
MMT assembly site

Impacts to Data Sheet:
None

Reason for Change:
To improve manufacturability by qualifying MMT assembly site.

Change Implementation Status:
In Progress

Estimated First Ship Date:
July 15, 2015 (date code: 1529)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Markings to Distinguish Revised from Unrevised Devices:
Traceability code

Revision History:
May 13, 2015: Issued initial notification.

The change described in this PCN does not alter Microchip’s current regulatory compliance regarding the material content of the applicable products.

Attachment(s):
PCN_JAON-04CYDE005_Qual_Plan.pdf
PCN_JAON-04CYDE005_Affected_CPN.pdf
PCN_JAON-04CYDE005_Affected_CPN.xls

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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